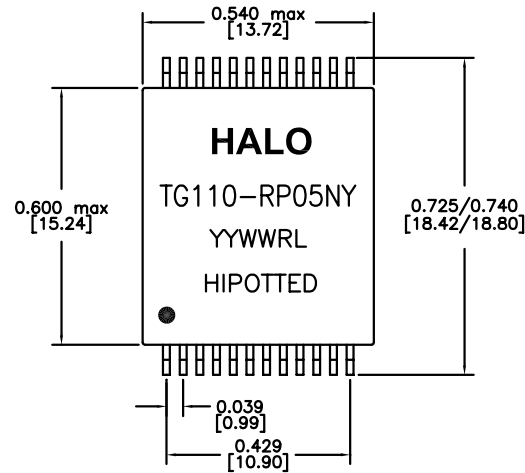




PART NO. : TG110-RP05NYRL

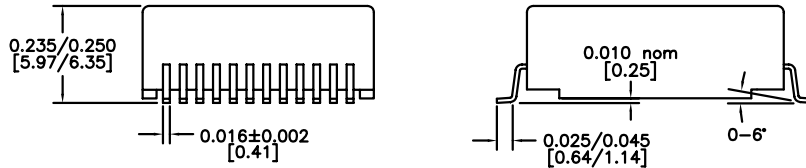
24PIN 0.039" LEAD PITCH SMT PACKAGE
FAST ETHERNET 10/100BASE-TX MAGNETICS
COMPLIANT WITH IEEE802.3af STANDARD

350mA CURRENT CARRYING CAPACITY
ON LINE SIDE FOR PoE APPLICATIONS

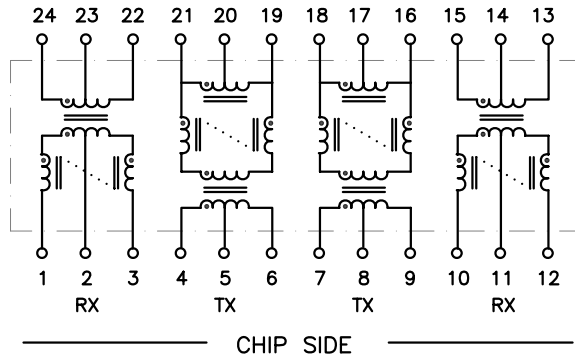
RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

OPERATING TEMPERATURE 0/+70°C



DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



ELECTRICAL SPECIFICATIONS @25° C

URNS RATIO 1CT:1CT±2%

OCL (100KHz,0.1Vrms,8mA)
P4-6,P7-9,P15-13,P24-22 350µH min

DCR
P4-6,P7-9,P15-13,P24-22 1.0Ω max

INSERTION LOSS
0.1-100MHz -1.1dB max

RETURN LOSS
0.5-30MHz -18dB min
40MHz -16dB min
50MHz -13dB min
60-80MHz -12dB min

CMR 0.1-100MHz -40dB typ

CROSSTALK 0.1-100MHz -40dB typ

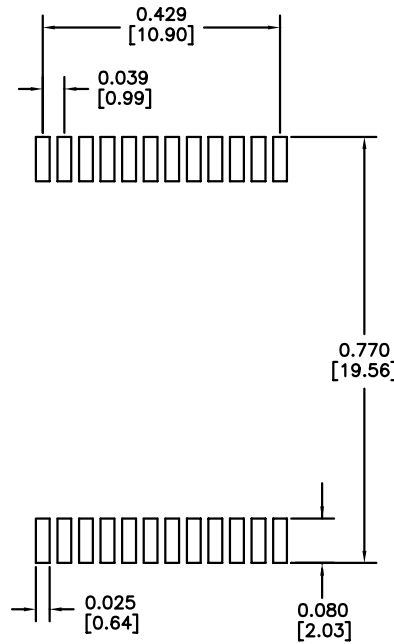
ISOLATION 1,500Vrms



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE	SIGNATURES	DATE	REV.	DESC.	DATE
FOR	FAST ETHERNET, PoE	DRAWN PETER LU	4/27/05	A	FIRST ISSUE	4/27/05
PART NO.	TG110-RP05NYRL	CHECKED LEI KEONG	5/6/06	B	PROD. RELEASE	5/6/06
SCALE	NONE	APPROVED PETER LU	5/6/06			
PAGE	1 OF 2	FILE RP05NYRL.DWG				



RECOMMENDED SOLDER PAD DIMENSIONS
DIMENSIONS: Inch [mm]

HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE		SIGNATURES	DATE	REV.	DESC.	DATE
FOR	FAST ETHERNET, PoE		DRAWN PETER LU	4/27/05	A	FIRST ISSUE	4/27/05
PART NO.	TG110-RP05NYRL		CHECKED LEI KEONG	5/6/06	B	PROD. RELEASE	5/6/06
SCALE	NONE	PAGE 2 OF 2	APPROVED PETER LU	5/6/06			
			FILE RP05NYRL.DWG				